EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3	yedinak and (combinational boolean logic) with circuit	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/12 15:23
L2	41	Takeoka.in. and (combinational boolean logic) with circuit	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/12 15:30
L3	14	Takeoka.in. and (combinational) with circuit	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/12 15:24
L4	13	Takeoka.in. and (combinational boolean logic) with circuit	US-PGPUB	OR	OFF	2006/10/12 15:30
S17 2	1624	combinational circuit	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2006/10/11 16:55
S17 3	16	(US-20020194564-$ or US-20030006795-$ or US-20030032263-$ or US-20040195672-$ or US-20040197941-$ or US-20040199840-$ or US-20040221143-$).did. or (US-6094736-$ or US-4728751-$ or US-5673276-$ or US-6263422-$ or US-6237054-$ or US-6330666-$ or US-5383192-$ or US-5341096-$ or US-6734549-$).did.	US-PGPUB; USPAT	OR	OFF	2006/10/11 16:54
S17 4	0	S172 and S173	US-PGPUB; USPAT	OR	OFF	2006/10/11 16:55
S17 5	1	(US-20040195672-$).did.	US-PGPUB	OR	OFF	2006/10/11 16:55
S17 6	0	S172 and S175	US-PGPUB; USPAT	OR	OFF	2006/10/11 16:55

EAST Search History

S17 7	22911	internal circuit	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2006/10/11 16:57
S17 8	1	S177 and S175	US-PGPUB; USPAT	OR	OFF	2006/10/11 16:57
S17 9	4501	(internal or boundary) scan	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2006/10/11 16:58
S18 0	1	S179 and S175	US-PGPUB; USPAT	OR	OFF	2006/10/11 16:59
S18 1	214	internal scan same boundary scan	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2006/10/11 16:58
S18 2	1	S181 and S175	US-PGPUB; USPAT	OR	OFF	2006/10/11 16:59
S18 3	1	(US-5673276-$).did.	USPAT	OR	OFF	2006/10/12 10:22
S18 8	1719	(multi-chip package or MCP or multi-chip module or MCM) near3 (semiconductor or silicon)	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/10/12 10:22
S18 9	26	boundary scan and S188	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/10/12 10:22
S19 0	12	scan chain and S188	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/10/12 10:22
S19 1	6	S189 and S190	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/10/12 10:22
S19 3	5	("6094736" | "6272069" | "6473873" | "6519171" | "6711042").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/10/12 10:22
S19 4	42747	fukuyama or Oki Electric	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	ADJ	ON	2006/10/12 10:22

EAST Search History

S19 5	6	boundary scan and scan chain and S194	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	ADJ	ON	2006/10/12 10:22
S19 6	4	S193 and (boundary or scan or chain or test or testing or tested)	US-PGPUB; USPAT; USOCR	OR	OFF	2006/10/12 10:22
S19 7	22	(silicon semiconductor) same ceramic same (submount mount) same (TCE thermal adj coefficient)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 10:23
S19 8	6	S191 and (interconnect interconnection interconnecting connection connect connecting line wire wiring)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 10:23
S19 9	5	S191 and line	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 10:23
S20 0	129	boundary scan and scan chain and IP	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	ADJ	ON	2006/10/12 10:23
S20 1	47	chip adj IP and IP and intellectual adj property	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 10:23
S20 2	97	S200 and (silicon semiconductor gaas inp)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 10:23
S20 3	18	IP Super-Sub	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	ADJ	ON	2006/10/12 10:23
S20 4	69	chip adj IP and IP	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 10:23

S205	52	interface with two-wire adj type	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 10:23
S206	2	(US-20030032263-$ or US-20030006795-$).did.	US-PGPUB	OR	OFF	2006/10/12 10:23
S207	1170	boundary scan test	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/10/12 10:23
S208	22	S207 and internal scan chain	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/10/12 10:23
S209	18	S208 and (board pcb mount mounting substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 10:23
S210	11	S209 and (wire wiring bond bonding)	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/12 10:23
S211	8	S210 and input terminal and output terminal	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/10/12 10:23
S212	27123	multi-chip package or MCP or multi-chip module or MCM	US-PGPUB; USPAT; USOCR	ADJ	ON	2006/10/12 10:23
S213	142	S207 and internal scan	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2006/10/12 10:23
S214	128	S213 and (board pcb mount mounting substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 10:23
S215	99	S214 and (wire wiring bond bonding)	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/12 10:23

EAST Search History

S21 6	5	(("20010194564") or ("6519728") or ("6400173") or ("20020171449") or ("20030006795") or ("20030032263")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/10/12 10:23
S21 7	6	(("20020194564") or ("6519728") or ("6400173") or ("20020171449") or ("20030006795") or ("20030032263")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/10/12 10:23
S21 8	11	S209 and (wire wiring bond bonding)	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/12 10:23
S21 9	1	(US-20040195672-$ or US-20040197941-$).did. or (US-6734549-$).did.	US-PGPUB; USPAT	OR	OFF	2006/10/12 10:23
S22 0	2964	(714/724,726,727).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/10/12 10:23
S22 1	337	S207 and S220	US-PGPUB; USPAT; USOCR	ADJ	OFF	2006/10/12 10:23
S22 2	41	S205 and (test tested testing tester test adj frame)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 10:23
S22 3	83	S215 and chip	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/12 10:23
S22 4	97	S202 and (test tested testing tester test adj frame)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2006/10/12 10:23
S22 5	11	S210 and input and output	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/12 10:23
S22 6	1176	(257/48).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/10/12 10:23
S22 7	5	(("6261467") or ("5933709") or ("4835593") or ("6255729") or ("6456099")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/10/12 10:23